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Customer No.: 31561
Application No.: 10/711,540
Docket No.: 13365-US-PA

AMENDMENT

To the Claims:

Claim 1-24 (cancelled).

Claim 25. (currently amended) A chip with polymer thereon, comprising at least:

a chip having an active surface;

a polymer, disposed at periphery of the active surface of the chip extending to sidewalls of the chip; and

112, 1st paragraph

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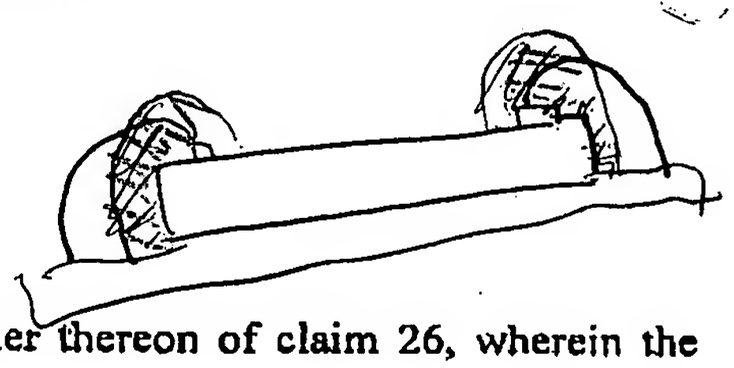
a plurality of wires electrically connecting the chip and a carrier for carrying the chip, wherein an end a portion of each of the wires connected with near the active surface of the chip is covered by the polymer and the other end portion of each of the wires is exposed outside of the polymer.



Claim 26-27. (cancelled)

Claim 28. (original) The chip with polymer thereon of claim 26, wherein the polymer further covers a portion of the carrier.

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Claim 29. (original) The chip with polymer thereon of claim 26, wherein the carrier comprises a leadframe or a circuit substrate.

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Claim 30. (original) The electrical package structure of claim 25, wherein the polymer is shaped as a ring covering whole periphery of the active surface of the chip.

Claim 31. (original) The electrical package structure of claim 25, wherein the polymer is shaped as strips covering two opposite edges of the active surface of the chip.

Claim 32. (original) The electrical package structure of claim 25, wherein the polymer is shaped as a plurality of pieces covering four corners of the active surface of the chip.

Claim 33. (original) The electrical package structure of claim 25, wherein the polymer comprises a stress buffer polymer.

Claim 34. (original) The electrical package structure of claim 33, wherein the stress buffer polymer comprises epoxy resin or polyimide.

obvious to modify the polymer covering @ 4 corners of the